



ALLIANCE MEMORY MDS REPORT

Part Number:		AS4C32M32MD1A-5BIN						
Part Weight:		145.5mg						
NO.	Material	Substance	Chemical Name	CAS No.	Material Weight(mg)	Substance Weight(mg)	wt % of Total unit wt	Hazardous Substance
1	Substrate	Continuous Filament Fiber Glass	5~12	65997-17-3	25.200	3.2760	2.252%	N.D
		Copper	30~45	7440-50-8		9.8280	6.755%	N.D
		Bismaleimide / Triazine	20~45	13676-54-5/25722-66		7.9380	5.456%	N.D
		Epoxy Resin	15~30	26265-08-7		2.7720	1.905%	N.D
		Inorganic filler	3~5	13776-74-4/7631-86-9		0.5040	0.346%	N.D
		Morpholine derivative(solder resist)	7~13	Trade secret		0.5040	0.346%	N.D
		Nickel	1~5	7440-02-0		0.3024	0.208%	N.D
		Gold	0.5~3	13967-50-5		0.0756	0.052%	N.D
2	WBL Tape	Acrylic Epoxy Adhesive	60~70	Trade secret	1.020	0.6630	0.456%	N.D
		Acrylic Pressure Sensitive Adhesive	40~30	Trade secret		0.3570	0.245%	N.D
3	Gold Wire	Gold	99.99	7440-57-5	1.920	1.9200	1.320%	N.D
4	EMC	Silica, vitreous	80~90	60676-86-0	90.510	78.7437	54.119%	N.D
		Phenol Polymer with 1,4 -bis benzene	1~10	26834-02-6		0.9051	0.622%	N.D
		Carbon Black	0~1	1333-86-4		0.4526	0.311%	N.D
		4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethyl(1,1'-biphenyl)	1~10	85954-11-6		0.9051	0.622%	N.D
		Others	10~20	Trade secret		9.5036	6.532%	N.D
5	Solde ball	Tin	98.25	7440-31-5	19.950	19.6009	13.471%	N.D
		Silver	1.2	7440-22-4		0.2394	0.165%	N.D
		Copper	0.5	7440-50-8		0.0998	0.069%	N.D
		Nickel	0.05	7440-02-0		0.0100	0.007%	N.D
6	Mo-DDR	Die			6.900	6.9000	4.742%	N.D
					145.500	100.000%		